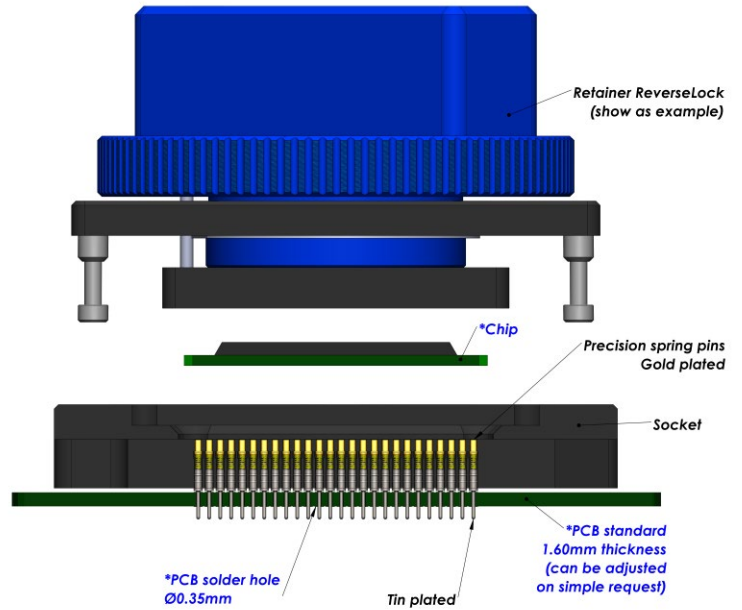
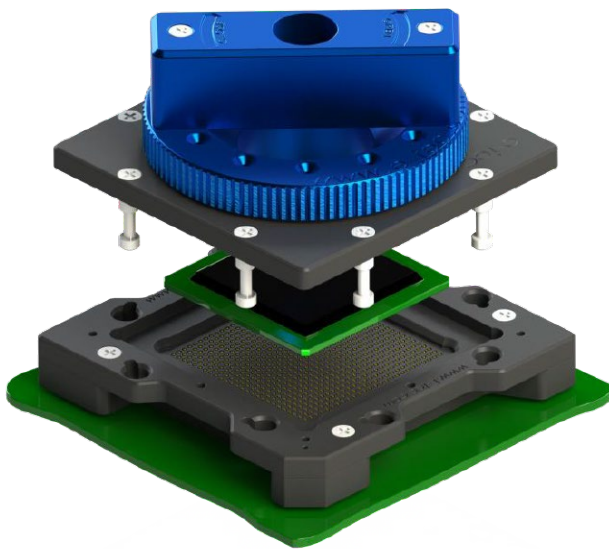
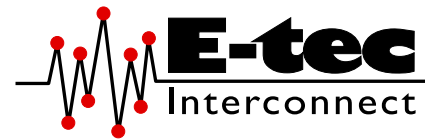


Through-hole (THT) soldering Test Socket

For LGA / QFN / MLF / MLP / LCC Package

0.50 mm pitch (from 0.50 mm up to 0.79 mm)



E-tec Interconnect AG is the world leading Test socket manufacturer

The Through-hole socket uses the same footprint as your chip. Socket is simply placed and wave soldered onto the PCB in the same way as the chip and it only requires a small amount of additional board space. Through-hole sockets are available with all retention systems. Please note, we will always request the chip data to ensure we offer a compatible socket.

Specifications contact type code 0570			
Application	Through-hole technology	Force	30 gr
Mounting	THT	Current rating	1 A
Bandwidth (GHz@-1dB)	2.7 GHz	Capacitance pF	< 1 pF
Contact resistance	<100mOhm	Inductance nH	< 2 nH
Chip contact tip shape	Single Point tip or Concave tip	Temperature range	-55°C to +150°C
PCB tip shape	Through-hole	Mating cycles	100 K

How to order

LP # #### -0570 - ##### 95 #

<p>Shape of tip</p> <p>P : Pointed</p> <p>Options:</p> <p>C : Crown</p>	<p>Nbr of contacts</p> <p>Depends on ballcount of chip</p>	<p>Contact type</p> <p>70 : Standard THT</p>	<p>Plating</p> <p>95: Tin / Gold</p> <p>Other on request</p>	<p>Option code (see page 16-19)</p> <p>D : Dead bug</p> <p>M : Multi frames</p> <p>U : Multi packages</p> <p>C : Converter plate</p> <p>S : Custom opening slot</p> <p>L : Locating pegs</p> <p>A : Alignment plate</p> <p>H : Heatsink</p> <p>F : Fan + Heatsink</p> <p>P : Thermal drain pad</p> <p>W : Transparent lid</p> <p>I : Steel retention lid</p> <p>B : Aluminium retention lid</p> <p>T : Torque tool fixture</p> <p>G : Handling button</p>
<p>Retention frame type (Lid) (see page 12-15)</p> <p>W: TwistLock</p> <p>F : FastLock</p> <p>B : SpringLock</p> <p>H : Open Clamshell Alu (<200 contacts)</p> <p>J : Clamshell Alu (>200 contacts)</p> <p>L : Open Lever Clamshell Alu (>200 contacts)</p>		<p>S : ScrewLock</p> <p>Q : Open QuickLock (<200 contacts)</p> <p>D : QuickLock (>200 contacts)</p> <p>M : Injection Molded ClamShell</p> <p>R : ReverseLock</p> <p>T : SlimLock</p>		<p>Grid code / Config. code</p> <p>Will be given by the factory after receipt of the chip datasheet</p>

